

Amendments to the Abstract

Please amend the specification as follows:

~~The present invention relates to an encapsulation method of leadless semiconductor package. The method comprises the steps of: (a) attaching a plurality of dice to the die pads on the cavities of a leadframe, the leadframe having a plurality of cavities arranged in matrix configuration and classified into a plurality of columns and a plurality of rows; (b) electrically connecting the die on the die pad to a plurality of conducting portions of the leadframe; and (c) longitudinally injecting the mould compound into the cavities of the column via a plurality of longitudinal gates of the leadframe to package the dice on the cavities of the column, the longitudinal gates mounted between the cavities of the column. The mould of the invention does not need a film to prevent the molding flash, and can solve the problem of remaining the molding flash on the conducting portion. The method of the invention does not use the expensive cutting equipment so as to decrease the cost and to upgrade the efficiency. An encapsulation technique for leadless semiconductor packages entails: (a) attaching a plurality of dice (411) to die pads in cavities (41-45, 51-55) of a leadframe, the cavities arranged in a matrix of columns and rows; (b) electrically connecting the dice to a plurality of conducting portions (412-414) of the leadframe; and (c) longitudinally injecting molding material into the cavities along the columns via a plurality of longitudinal gates (46-49, 56-59) of the leadframe to package the dice in the cavities, the longitudinal gates situated between the cavities along the columns.~~